

ABSTRACT

[0051] An integrated heat spreader (IHS) having a groove and a cavity formed therein is disclosed. In one embodiment, the groove has an insulating layer formed therein, and a power conduit is mounted in the groove, the power conduit is electrically isolated from the IHS by the insulating layer, and the power conduit conducts a voltage relative to the IHS to deliver power to the cavity. In another embodiment, the IHS is soldered to a semiconductor die and a package substrate. In a further embodiment, the power conduit comprises an edge connector.